

L Number	Hits	Search Text	DB	Time stamp
1	1	("5683942").PN.	USPAT;	2003/07/10
2	1227	361/760.ccls.	US-PPGPUB	15:18
3	448	361/760.ccls. and adhesive	USPAT;	2003/07/10
4	224	(361/760.ccls. and adhesive) and @ad<=19980327	US-PPGPUB	15:18
6	29963	adhesive with (hole or opening)	USPAT;	2003/07/10
7	9495	(adhesive with (hole or opening)) and (substrate or chip)	USPAT;	2003/07/10
8	5045	((adhesive with (hole or opening)) and (substrate or chip)) and @ad<=19980327	US-PPGPUB	15:36
9	206	((adhesive with (hole or opening)) and (substrate or chip)) and @ad<=19980327) and (wiring adj pattern)	USPAT;	2003/07/10
10	22093	adhesive with (hole or opening)	US-PPGPUB	15:30
			EPO; JPO; DERWENT;	2003/07/10
11	3172	(adhesive with (hole or opening)) and (substrate or chip)	IBM_TDB	15:36
12	89	((adhesive with (hole or opening)) and (substrate or chip)) and (wiring adj pattern)	EPO; JPO; DERWENT; IBM_TDB	2003/07/10
				15:36

exhausted search 7/10/03

	U	1	Document ID	Issue Date	Pages	Title	Current OR
1	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5683942 A	19971104	31	Method for manufacturing bump leaded film carrier type semiconductor device	438/118

	Current XRef	Retrieval Classif	Inventor	S	C	P	2	3	4	5
1	257/E23.06 5; 257/E23.12 4; 29/827; 438/123		Kata, Keiichiro et al.	<input type="checkbox"/>						

	Image Doc. Displayed	PT
1	US 5683942	<input type="checkbox"/>

L Number	Hits	Search Text	DB	Time stamp
1	14490	protrusion with (hole or opening)	USPAT; US-PPGPUB	2003/07/10 17:38
2	1470	(protrusion with (hole or opening)) and substrate	USPAT; US-PPGPUB	2003/07/10 17:50
3	521	((protrusion with (hole or opening)) and substrate) and adhesive	USPAT; US-PPGPUB	2003/07/10 17:39
4	223	((protrusion with (hole or opening)) and substrate) and adhesive	USPAT; US-PPGPUB	2003/07/10 17:54
5	14801	((protrusion with (hole or opening)) and substrate) and adhesive) and @ad<19980327 protrusion with (hole or opening)	EPO; JPO; DERWENT; IBM_TDB EPO; JPO; DERWENT;	2003/07/10 17:38 2003/07/10 17:39
7	544	(protrusion with (hole or opening)) and substrate	IBM_TDB EPO; JPO; DERWENT;	2003/07/10 17:39
8	31	((protrusion with (hole or opening)) and substrate) and adhesive	IBM_TDB EPO; JPO; DERWENT;	2003/07/10 17:39
9	949	((protrusion with (hole or opening)) and substrate) not (((protrusion with (hole or opening)) and substrate) and adhesive)	IBM_TDB USPAT; US-PPGPUB	2003/07/10 17:52
10	436	((protrusion with (hole or opening)) and substrate) not (((protrusion with (hole or opening)) and substrate) and adhesive)) and @ad<19980327	USPAT; US-PPGPUB	2003/07/10 17:54

	U	1 [1]]	Document ID	Issue Date	Pages	Title	Current OR
1	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6060775 A	20000509	8	Semiconductor device	257/693
2	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6017025 A	20000125	22	Component retainer	269/48.1
3	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6016601 A	20000125	7	Method of preparing the nozzle plate	29/890.1
4	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6000783 A	19991214	7	Nozzle plate for ink jet recording apparatus and method of preparing said nozzle plate	347/45
5	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5812378 A	19980922	27	Microelectronic connector for engaging bump leads	361/769
6	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5387440 A	19950207	7	Nozzle plate for ink jet recording apparatus and method of preparing a said nozzle plate	427/443.1

	Current XRef	Retrieval Classif	Inventor	S	C	P	2	3	4	5
1	257/690; 257/691; 257/700; 257/738; 257/E23.12 5		Ano, Kazuaki	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
2	269/254R		Balz, James Gregory et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
3	347/47		Takemoto, Kiyohiko et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
4	347/47		Takemoto, Kiyohiko et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
5	257/E23.06 7; 257/E23.06 9; 257/E23.07 8; 361/767; 361/771; 361/772; 361/774; 361/776; 361/777; 439/82		Fjelstad, Joseph et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>					
6	205/127; 347/45		Takemoto, Kiyohiko et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>					

	Image Doc. Displayed	PT
1	US 6060775	<input type="checkbox"/>
2	US 6017025	<input type="checkbox"/>
3	US 6016601	<input type="checkbox"/>
4	US 6000783	<input type="checkbox"/>
5	US 5812378	<input type="checkbox"/>
6	US 5387440	<input type="checkbox"/>